

WHAT IS CLAIMED IS:

1. A method of forming a composite insulating layer, comprising:
 - a step of forming an adhesive layer containing a partially imidated polyamic acid on a metallic foil;
 - a step of applying a solution containing a polyamic acid to the surface of the adhesive layer;
 - a step of subjecting the coated solution to phase separation to form a porous layer; and
 - a step of subjecting the adhesive layer and the porous layer to imide conversion.
2. The method as claimed in claim 1, wherein the partially imidated polyamic acid has a ratio $RA (= A1/A2)$ of an absorbance $A1$ derived from a $C=O$ bond of an imido ring to an absorbance $A2$ derived from a $C=O$ bond of an amide acid in the infrared absorption spectrum of 0.1-5.0.
3. The method as claimed in claim 1, wherein the step of forming an adhesive layer comprises applying a solution containing a polyamic acid to the surface of the metallic foil, and then conducting drying of a solvent contained therein and partial imidation of the polyamic acid, by heating.
4. A composite insulating layer formed by the method as claimed in claim 1.
5. A process of producing a wiring board, comprising a step of forming a insulating layer and a step of forming a wiring layer, wherein the step of forming a insulating layer is carried out to form the insulating layer by the method as claimed in claim 1.